Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.009” X .009”**

**.025”**

**.025”**

**Top Material: Al**

 **Backside Material: Au**

**Bond Pad Size: .009” X .009”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .025” X .025” DATE: 10/18/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 1N755A**

**DG 10.1.2**

#### Rev B, 7/1